Factory Witness

Characterization

Light-Induced Degradation CID LID Characterization Mechanical Potential-**Backsheet Thermal** Damp UVID **LETID Hail Stress PAN File** Field Induced **Durability** Stress & IAM Profile Cycling Heat **Sensitivity** Sensitivity Sequence **Exposure Degradation** Sequence Sequence Hail **SML** 85°C. 85%RH TC 200 UV PAN File Field DH 1000 DH 200 LETID 162 hrs (two sizes) (tracker or MSV (+ and/or -)60 kWh/m² Exposure 75°C, 2*(Isc-Imp) corner-mount) 192 hrs 60°C front 6 Months IAM Profile Characterization Characterization Characterization Characterization DML1000 Characterization Characterization Characterization Characterization DML 1000 DH 1000 TC 200 65 kWh/m² UV Field Characterization 80°C rear LETID 162 hrs Characterization Characterization Characterization 60 kWh/m² Exposure 75°C, 2*(lsc-lmp) 60°C front 6 Months TC 50 + HF 10 Characterization TC 200 TC 50 + HF 10 Characterization Characterization Characterization Characterization TC 50 + HF 10 Characterization Characterization OPTIONAL UV 65 kWh/m² Characterization Factory Witness All Bills of Materials submitted for testing are witnessed in production from opening of raw materials TC 50 + HF 10 packages through every step of the production process to final packaging with tamper-proof tape. **Testing Abbreviations Characterizations** UV 65 kWh/m² TC: Thermal cycling IV: Flash test at STC DH: Damp heat EL: EL image at Isc **UV: Ultraviolet** LIC: Flash test at 200W/m² Characterization HF: Humidity freeze LCEL: EL image at 1/10*Isc

VI: Visual inspection

Color: Backsheet color measurement

Note: Not all measurements are taken at each step

WL: Wet leakage

Diode: Diode test

LETID: Light and elevated temperature-induced degradation

IAM: Incidence angle modifier

MSV: Maximum system voltage

DML: Dynamic mechanical load

CID: Current induced degradation

UVID: Ultraviolet induced degradation SML: Static mechanical load

PAN File: PVSyst .pan file

UV 6.5 kWh/m²

TC 50 + HF 10

UV

Characterization